



Material Content Data Sheet



Sales Product Name		TLE4269GL		Issued		14. September 2018		
MA#		MA003558914						
Package		PG-DSO-20-66		Weight*		486.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.966	0.61	0.61	6101	6101
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6386	
wire	non noble metal	copper	7440-50-8	126.041	25.93	26.61	259292	266077
	non noble metal	copper	7440-50-8	0.172	0.04	0.04	353	353
	encapsulation	organic material	carbon black	1333-86-4	0.695	0.14		1430
encapsulation	plastics	epoxy resin	-	31.984	6.58		65797	
	inorganic material	silicondioxide	60676-86-0	314.968	64.80	71.52	647952	715179
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5649	5649
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3336	3336
glue	plastics	epoxy resin	-	0.402	0.08		826	
	noble metal	silver	7440-22-4	1.205	0.25	0.33	2479	3305
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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